

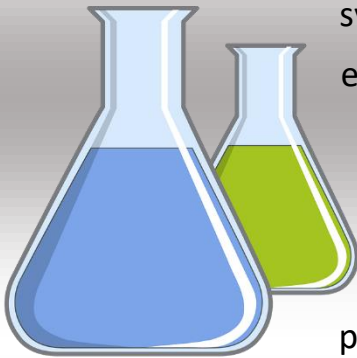
Evotech EVOLUTION RESIN TECHNOLOGY

Lectromat, Inc., long recognized as a manufacturer of B-stage resin coated films, papers, and cloth, and impregnated felts, now introduces an extension of our capabilities in providing custom formulated epoxy resins and compounds.

EVOTECH epoxy resins evolve from the concept that today's environmental, health and safety, productivity, and performance requirements can best be solved through custom formulated products. Growing industry concerns over current and future environmental regulations has prompted us to evaluate and utilize the latest technology in solventless and non-hazardous solvent bearing epoxy resin



systems. **EVOTECH** epoxy resins are the total answer to plant environment and employee health and safety issues.



EVOTECH is evolution resin technology; not generic yesteryear technology offered as reasonable alternatives that can only offer partial solutions. Our continuous effort to prove product and application expertise can result in overall improvements in performance, productivity, health and safety, and environmental compliance.

EVOTECH is customer driven evolutionary innovation; providing process and performance solutions today, tomorrow and the future. The products listed in this brochure represent standard formulations for the protection of most electrical and electronic devices. An investment in time to discuss your resin application will be rewarded with our total commitment to find the right solution to your individual problem. Our 40 plus years of service in the electrical insulation industry and combined application experience of over 100 years is testimony to our problem-solving capability.

UNFILLED – ROOM TEMPERATURE CURE

RESIN	HARDENER	MIX RATIO (by wt.)	MIXED VISC. @25°C, CPS	POT LIFE ⁽¹⁾ @ 25°C	APPLICATION ⁽²⁾	CHARACTERISTICS
LE-201	LH-101	100:25	2500	33 mins	P, C	Good chemical & moisture resistance
	LH-102	100:50	1160	9.5 mins	P, C	Fast cure in thin films & small masses
	LH-103	100:50	1440	90 mins	P, C, M	Resilient, low exotherm/low shrinkage
	LH-104	100:50	1180	22 mins	P, C	Moderate pot life, resilient
	LH-105	100:100	1180	2 hours	P, C, M	Long pot life, low exotherm/low shrinkage
	LH-111	100:10	N.A.	15 secs ⁽³⁾	A	Rapid cure, surface mount adhesive
LE-202	LH-103	100:100	900	90 mins	P, C, M	Resilient, high impact resistance
LE-204	LH-112	100:25	2500	20 mins	TF	General purpose, random wound stators
95-117-20 PART A	95-117-20 PART B	100:30	2050	N.A.	TF	High bond, fast cure

FILLED – ROOM TEMPERATURE CURE

RESIN	HARDENER	MIX RATIO (by wt.)	MIXED VISC. @25°C, CPS	POT LIFE ⁽¹⁾ @ 25°C	APPLICATION ⁽²⁾	CHARACTERISTICS
LE-401	LH-101	100:10	70,000	1 hour	P, C	Good chemical & moisture resistance
	LH-102	100:20	5,000	15 mins	P, C	Fast cure in thin films & small masses
	LH-103	100:20	3,000	> 4 hours	P, C, M	Resilient, low exotherm/low shrinkage
	LH-104	100:20	3,500	39 mins	P, C	Moderate pot life, resilient
	LH-105	100:40	2,800	2 hours	P, C, M	Long pot life, low exotherm/low shrinkage
94-073 A	94-073 B	100:20	PASTE	2 hours	B	Stator end wind protection
02-346 A	02-346 B	100:25	PASTE	4 hours	B	General purpose for sealing & patching coils & windings

(1) 250 g mass

(2) P=Potting, C=Casting, M=Molding, TF=Trickle Feed, B=Brush On, VPI=Vacuum Pressure Impregnation, SD=Static Dip

(3) 10 g mass

(4) @ 25°C

(5) 22 ml

(6) Brookfield Helipath

(7) Mass Lid

The information contained herein is intended only to assist customers in determining whether our products are suitable for their application. Since we have no control over how products are used, we cannot guarantee the performance of these products. We request that customers inspect and test our products before use and satisfy themselves as to suitability. The exclusive remedy for all proven claims is replacement of our materials and in no event shall Lectromat, Inc. be liable for special, incidental, or consequential damages.



RESIN	BROOKFIELD VISC. @ 25°C, CPS	V.O.C.	GEL TIME ⁽¹⁾ @150°C	SHORE D ⁽⁴⁾ HARDNESS	APPLICATION	CHARACTERISTICS
LE-100	400	SOLVENTLESS	38.9 mins	85	VPI, SD	Low viscosity, low dissipation factor
LE-101	125	SOLVENTLESS	11 mins ⁽⁵⁾	88	P, C	Rigid, unfilled with high heat deflection
LE-102	10, 850/4300	SOLVENTLESS	9.5 mins	83	VPI, SD	Thixotropic impregnant/encapsulant
LE-102NT	1120	SOLVENTLESS	6.25 mins		VPI, SD	Non-thixotropic version of LE-102
LE-300	75,000 49,250	SOLVENTLESS	5.7 mins	86	P, C	Fast cure, excellent adhesion to metals
LE-330	600,000 120,000	SOLVENTLESS	15 mins	90	B	High strength at elevated temperatures
LE-345	2,000,000 ⁽⁶⁾ 705,000	SOLVENTLESS	9 mins	90	B	Higher viscosity LE-330
96-177-10	1100/700	1.49 LBS/GAL		80	SD	General purpose, good film build one coat
97-221	900	1.66 LBS/GAL	10 mins ⁽³⁾	85	SD, TF	Pure epoxy, coolant resistant
97-222	460	1.05 LBS/GAL	15 mins ⁽³⁾	85	SD, TF	Epoxy/phenolic, coolant resistant
97-236-8	21,000/8,000	SOLVENTLESS	15 mins ⁽³⁾	85	VPI	Stable, thixotropic impregnant/encapsulant
97-237	700	0.88 LBS/GAL	10 mins ⁽³⁾	85	SD, TF	High bond, fast cure, chemical resistant
09-386	230-350	3.33 LBS/GAL	35 min ⁽⁷⁾	85	SD	Low viscosity, chemical and moisture resistant
LE-166	25,000/5,500	SOLVENTLESS	15 mins	80	VPI	Thixotropic, excellent film build, limited run off
LE-106	32,000/6,000	SOLVENTLESS	15 mins	90	VPI	Thixotropic, excellent film build, limited run off, glass fiber filled to reinforce toughness

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